

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC62HxxxxxDR-G
Typical Mass: 6 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.724	Silicon	120700	7440-21-3
Lead pad	1.100	Nickel	183400	7440-02-0
	0.087	Silver	14600	7440-22-4
	0.016	Gold	2700	7440-57-5
Die attach	0.016	Epoxy Resin	2700	—
	0.012	Silica	2100	60676-86-0
Bonding wire	0.040	Gold	6700	7440-57-5
Resin	3.603	Silica	600500	60676-86-0
	0.220	Epoxy Resin	36700	—
	0.180	Phenol Resin	30000	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."